



SOT996-2

plastic extremely thin small outline package; no leads; 8 terminals; body 3 x 2 x 0.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	XSON8
Package type industry code	XSON8
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package style suffix code	U (UTLP based)
Package body material type	P (plastic)
IEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	21-12-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	[tbd]	-	0.5	0.5	mm
A ₂	package height	[tbd]	-	0.5	[tbd]	mm
e	nominal pitch	-	-	[tbd]	-	mm
n ₂	actual quantity of termination	-	-	8	-	

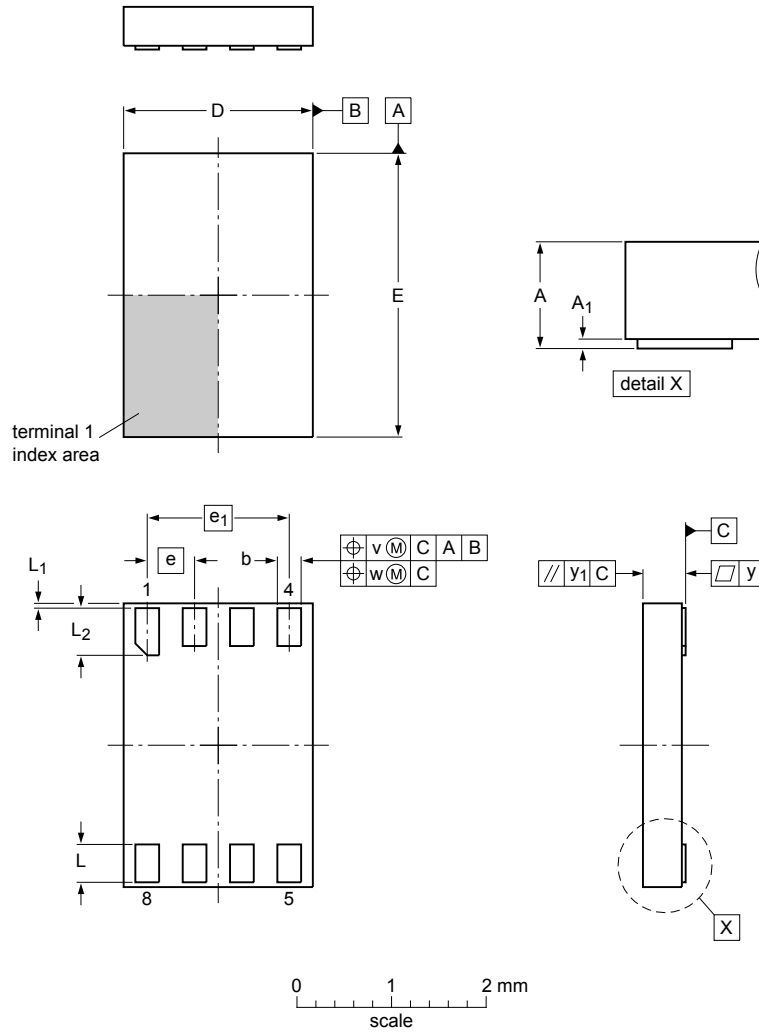


plastic extremely thin small outline package; no leads;
leads; 8 terminals; body 3 x 2 x 0.5 mm

2. Package outline

XSON8: plastic extremely thin small outline package; no leads;
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Dimensions (mm are the original dimensions)

Unit ⁽¹⁾	A	A ₁	b	D	E	e	e ₁	L	L ₁	L ₂	v	w	y	y ₁
max		0.05	0.35	2.1	3.1		0.5	0.15	0.6			0.1	0.05	0.1
nom	0.5					0.5	1.5	0.3	0.05	0.4				
min		0.00	0.15	1.9	2.9									

sot996-2_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT996-2					-07-12-21- 12-11-20

Fig. 1. Package outline XSON8 (SOT996-2)

plastic extremely thin small outline package; no leads; 8 terminals; body 3 x 2 x 0.5 mm

3. Soldering

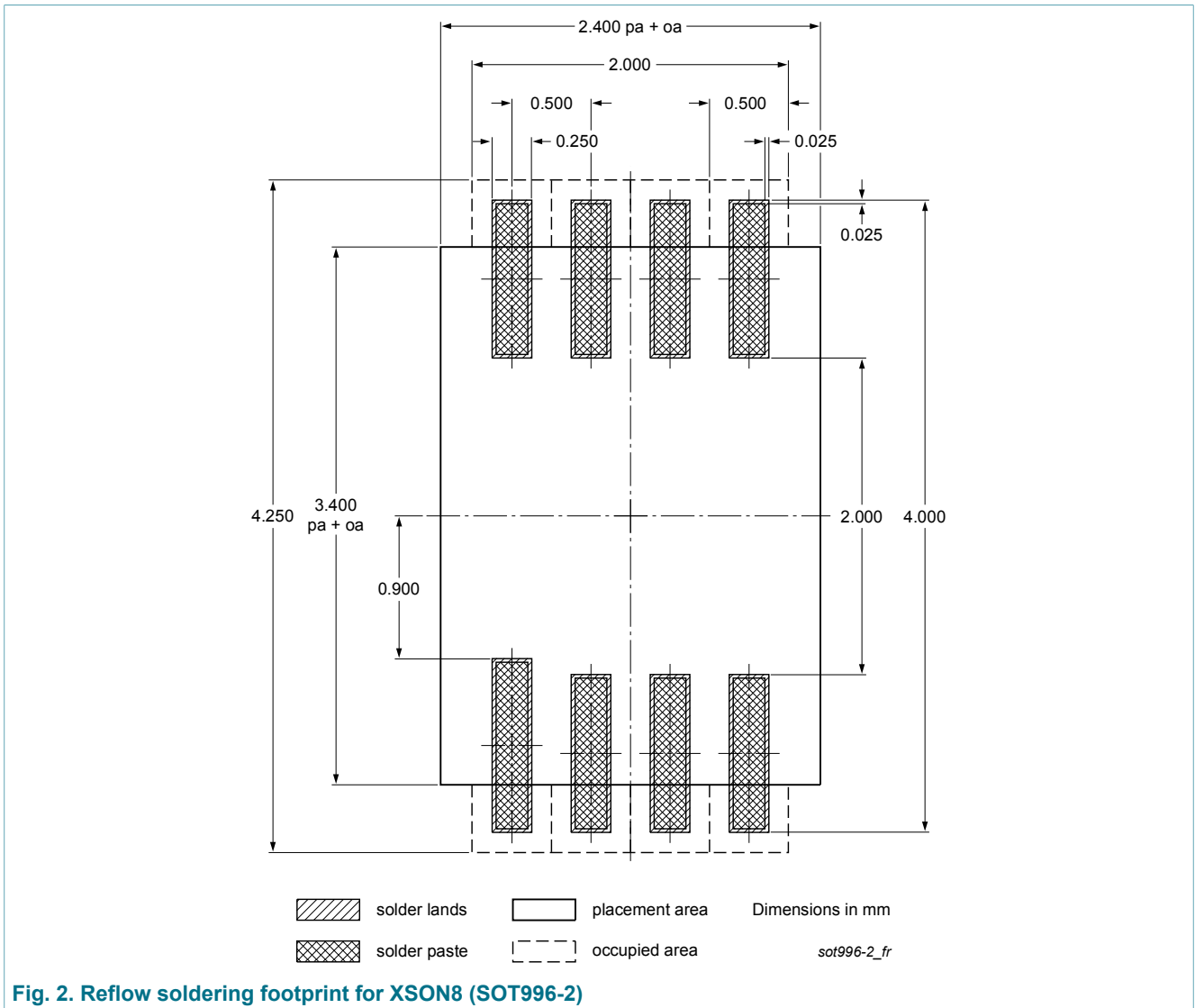


Fig. 2. Reflow soldering footprint for XSON8 (SOT996-2)

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4. Legal information

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